

Tool ID: 502  
Tool Location: 118

Equipment Information Sheet  
**E-Beam Lithography Hot Plates**

Manager: Alan R. Bleier

607-254-4931

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

**SAFETY**

- Never set hot plates above 225C
- Always leave hot plates at their listed temperature
- Only use metal tweezers when removing samples

**USAGE RESTRICTIONS**

**SCHEDULING/SIGN-UP RESTRICTIONS**

Minimum Tool Time: 0 minutes

- If you need to use the hot plates for longer than 30 minutes contact staff first for approval

**MATERIALS COMPATIBILITY CATEGORY**

**Tool Category 5: Class A and B Metals and Compounds**

Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

**High Vapor Pressure Metals and Compounds** are materials that have a vapor pressure above 1e-6 Torr at 400 C.

**Additional Material Restrictions and Exceptions**

- None

Last Updated: 01/11/2022